

**STACKED ELECTRONIC STRUCTURES INCLUDING OFFSET
SUBSTRATES**

Abstract

An electronic device may include first, second, and third substrates wherein
5 the second electronic substrate is between the first and second electronic
substrates. A first electrical and mechanical connection may be provided between
the first and third electronic substrates, and a second electrical and mechanical
connection may be provided between the second and third electronic substrates. In
addition or in an alternative, an electronic device may include a printed circuit
10 board, a first electronic substrate on the printed circuit board, a second electronic
substrate on the first electronic substrate, and a third electronic substrate on the
second electronic substrate. More particularly, the first electronic substrate may be
between the printed circuit board and the second electronic substrate, and the
second electronic substrate may be between the first and third electronic substrates.
15 In addition, the second electronic substrate may be offset relative to the first and
third electronic substrates so that a first end of the second electronic substrate
extends beyond the first and third electronic substrates and so that the first and
third electronic substrates extend beyond a second end of the second electronic
substrate.